

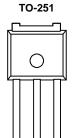
# N-Channel 60 V (D-S) MOSFET

PRODUCT SUMMARY						
V <sub>DS</sub> (V)	$R_{DS(on)}(\Omega)$	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)			
60	$0.032 \text{ at V}_{GS} = 10 \text{ V}$	35 <sup>d</sup>	21.7			
60	$0.037$ at $V_{GS} = 4.5 \text{ V}$	30 <sup>d</sup>	21.7			

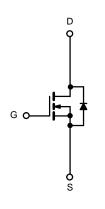
#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- 100 % R<sub>g</sub> and UIS Tested
- Compliant to RoHS Directive 2002/95/EC





D Top View



N-Channel MOSFET

#### **APPLICATIONS**

- Power Supply
  - Secondary Synchronous Rectification
- DC/DC Converter

<b>ABSOLUTE MAXIMUM RATINGS</b> T <sub>C</sub> = 25 °C, unless otherwise noted						
Parameter	Symbol	Limit	Unit			
Drain-Source Voltage	V <sub>DS</sub>	60	V			
Gate-Source Voltage	V <sub>GS</sub>	± 20	V			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	T <sub>C</sub> = 25 °C	I <sub>D</sub>	35 <sup>d</sup>	A		
Continuous Diam Current (1) = 130 C)	T <sub>C</sub> = 70 °C	'D	30 <sup>d</sup>			
Pulsed Drain Current	I <sub>DM</sub>	100	<b>1</b> ^			
Avalanche Current	I <sub>AS</sub>	40				
Single Avalanche Energy <sup>a</sup>	L = 0.1 mH	E <sub>AS</sub>	80	mJ		
Mariana Banas Birainatina	T <sub>C</sub> = 25 °C	D	59.5 <sup>b</sup>	10/		
Maximum Power Dissipation <sup>a</sup>	T <sub>A</sub> = 25 °C <sup>c</sup>	P <sub>D</sub>	2.7	W		
Operating Junction and Storage Temperature Range		T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS					
Parameter	Symbol	Limit	Unit		
Junction-to-Ambient (PCB Mount) <sup>c</sup>	R <sub>thJA</sub>	46	°C/W		
Junction-to-Case (Drain)	R <sub>thJC</sub>	2.1	C/VV		

#### Notes:

- a. Duty cycle  $\leq$  1 %.
- b. See SOA curve for voltage derating.c. When mounted on 1" square PCB (FR-4 material).
- d. Package limited.

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<b>SPECIFICATIONS</b> $T_J = 25^{\circ}$	Symbol	Test Conditions	Min.	Тур.	Max.	Unit
Static	Oyillooi	rest conditions	141111-	Typ.	IVIQA.	Onic
Drain-Source Breakdown Voltage	V <sub>DS</sub>	V <sub>DS</sub> = 0 V, I <sub>D</sub> = 250 μA	60			
Gate Threshold Voltage	1	$V_{DS} = V_{SS}, I_{D} = 250 \mu\text{A}$ $V_{DS} = V_{GS}, I_{D} = 250 \mu\text{A}$	2.0		3.5	V
Gate-Body Leakage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}, V_{GS} = \pm 20 \text{ V}$	2.0		± 250	nA
Gale-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 20 \text{ V}$ $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	IIA
Zana Cata Valtana Busin Current		$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$ $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			50	μΑ
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 123 \text{ C}$ $V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 150 \text{ °C}$			250	
On-State Drain Current <sup>a</sup>	1		F0		250	
On-State Drain Current	I <sub>D(on)</sub>	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	50	0.000		Α
Drain-Source On-State Resistance <sup>a</sup>	R <sub>DS(on)</sub>	V <sub>GS</sub> = 10 V, I <sub>D</sub> = 12 A		0.032		Ω
	, ,	$V_{GS} = 4.5 \text{ V}, I_D = 10 \text{ A}$		0.037		
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 15 V, I <sub>D</sub> = 10 A		110		S
Dynamic <sup>b</sup>	<u> </u>		T	<u> </u>		
Input Capacitance	C <sub>iss</sub>	V <sub>GS</sub> = 0 V, V <sub>DS</sub> = 30 V, f = 1 MHz		1100		pF
Output Capacitance	C <sub>oss</sub>			281		
Reverse Transfer Capacitance	C <sub>rss</sub>			130		
Total Gate Charge <sup>c</sup>	Qg	$V_{DS} = 30 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 10 \text{ A}$		46		
Total Gate Gharge				28		nC
Gate-Source Charge <sup>c</sup>	$Q_{gs}$	$V_{DS} = 30 \text{ V}, V_{GS} = 4.5 \text{ V}, I_{D} = 10 \text{ A}$		7		
Gate-Drain Charge <sup>c</sup>	$Q_{gd}$			6.7		
Gate Resistance	R <sub>g</sub>	f = 1 MHz	0.4	2	4	Ω
Turn-On Delay Time <sup>c</sup>	t <sub>d(on)</sub>			8	16	
Rise Time <sup>c</sup>	t <sub>r</sub>	$V_{DD} = 30 \text{ V, R}_{1} = 1.5 \Omega$		9	18	
Turn-Off Delay Time <sup>c</sup>	t <sub>d(off)</sub>	$I_D \cong 10 \text{ A}, V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$		35	53	ns
Fall Time <sup>c</sup>	t <sub>f</sub>			9	18	
Drain-Source Body Diode Ratings a	nd Characteris	stics T <sub>C</sub> = 25 °C <sup>b</sup>	<u> </u>			
Continuous Current	I <sub>S</sub>				50	
Pulsed Current	I <sub>SM</sub>				100	Α
Forward Voltage <sup>a</sup>	V <sub>SD</sub>	I <sub>F</sub> = 10 A, V <sub>GS</sub> = 0 V		0.75	1.5	V
Reverse Recovery Time	t <sub>rr</sub>	. 33		34	51	ns
Peak Reverse Recovery Current	I <sub>RM(REC)</sub>	I <sub>F</sub> = 10 A, dl/dt = 100 A/μs		2	3	Α
Reverse Recovery Charge	Q <sub>rr</sub>			34	51	nC

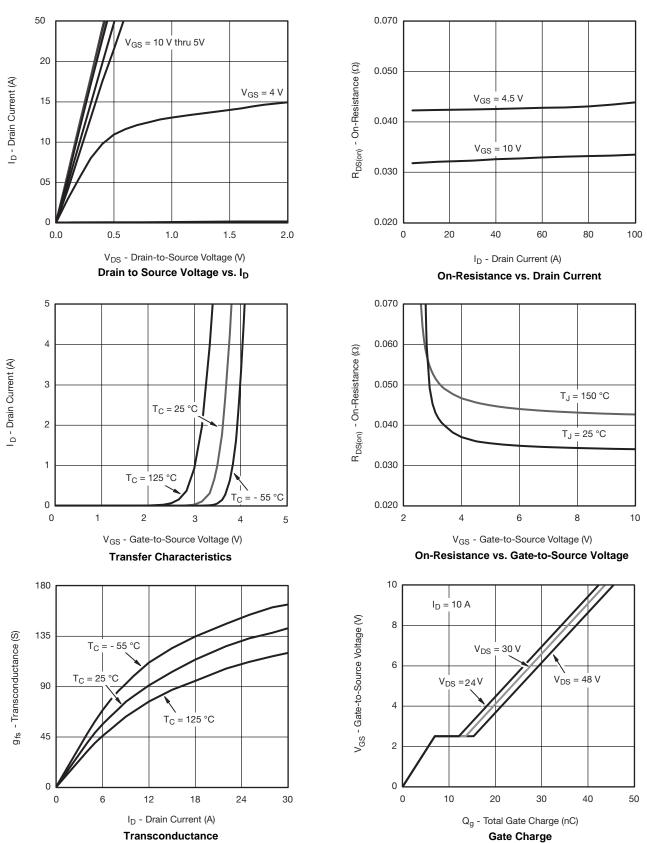
#### Notes:

- a. Pulse test; pulse width  $\leq 300~\mu s,$  duty cycle  $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.
- c. Independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

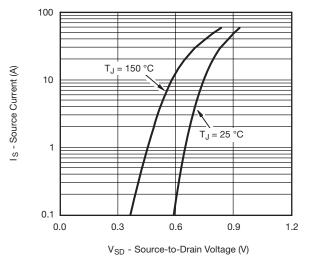


## TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

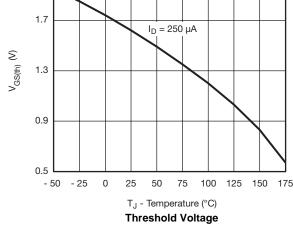




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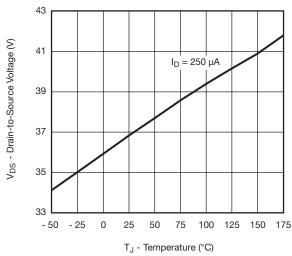
Source-Drain Diode Forward Voltage



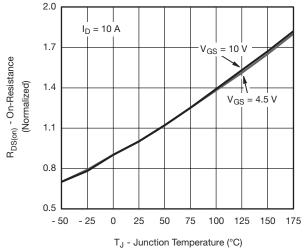
2.1

1500 1200 1200 C<sub>iss</sub> 900 0 0 0 5 10 15 20 25 30

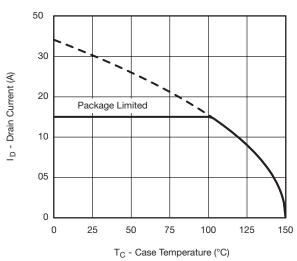
 $V_{DS}$  - Drain-to-Source Voltage (V)  $\label{eq:capacitance}$ 







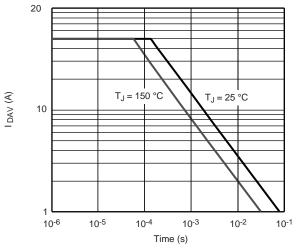
On-Resistance vs. Junction Temperature



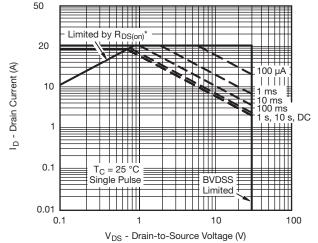
**Current Derating** 



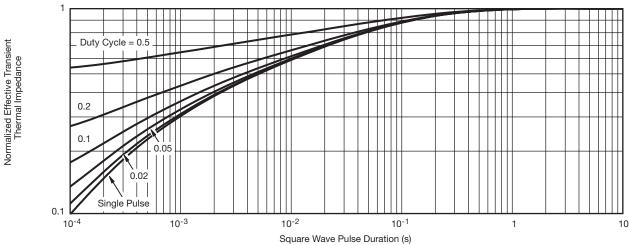
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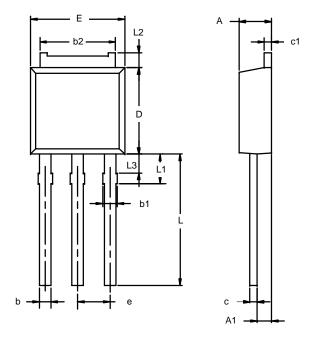
\*  $V_{GS}$  > minimum  $V_{GS}$  at which  $R_{DS(on)}$  is specified **Safe Operating Area** 



Normalized Thermal Transient Impedance, Junction-to-Case



## TO-251AA (DPAK)



Note: Dimension L3 is for reference only.

	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
<b>A</b> 1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
Е	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090 BSC		
L	8.89	9.53	0.350	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					

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